News Release

November 11, 2026
JX Advanced Metals Corporation

JX Advanced Metals Group Materials Utilized in Collaborative Glass Substrate Process Development for Advanced Packaging in Taiwan

JX Advanced Metals Corporation (President: Hayashi Yoichi; hereinafter "JX Advanced Metals") announces that its sputtering targets for semiconductors and conductive paste manufactured by its group company TATSUTA Electric Wire and Cable Co., Ltd. (President: Iida Kazuhiko; hereinafter "TATSUTA") have been utilized in a development project for next-generation semiconductor packaging technologies promoted by Hi-CHIP (Heterogeneous Integration and Chiplet System Package Alliance), an alliance established by the Industrial Technology Research Institute (ITRI) of Taiwan. The results of the initiative were presented by Hi-CHIP on October 21, 2026, at IMPACT 2026, an international conference on electronics packaging and semiconductor packaging held in Taiwan.

Hi-CHIP serves as an international collaboration platform that brings together not only Taiwan-based semiconductor-related companies, including the Taiwan operations of Intel Corporation, ASML Holding N.V., and Applied Materials, Inc., but also semiconductor, semiconductor materials, equipment, and packaging companies from around the world. By bringing together the expertise of participating companies, Hi-CHIP is advancing the development of technologies for the design, prototyping, evaluation, and mass production of advanced packaging solutions for heterogeneous integration and chiplets. The initiative is attracting attention for its efforts to commercialize next-generation packaging technologies that will support further advances in the performance of AI semiconductors and other devices.

JX Advanced Metals participates in a Hi-CHIP project aimed at developing next-generation semiconductor packaging technologies using glass interposers and glass core substrates. In the project, JX Advanced Metals' sputtering targets were used to form fine-pitch wiring on a glass interposer, successfully forming a seed layer that serves as the foundation for wiring formation. In addition, TATSUTA's conductive paste was used in the filling process for through-glass vias (TGVs) formed in a glass core substrate, enabling via filling and electrical conduction.

Glass interposers and glass core substrates offer advantages including the ability to minimize warpage and deformation even as substrate sizes increase, thanks to the extreme flatness and dimensional stability of glass, while enabling high-precision formation of fine-pitch wiring. These characteristics make glass a promising substrate material for next-generation semiconductor packages that require larger package sizes and greater integration density to accommodate multiple semiconductor chips at high density. As glass interposers and glass core substrates move toward practical application, sputtering targets used for fine-pitch wiring formation and conductive pastes used to fill TGVs are expected to become increasingly important. The JX Advanced Metals Group will contribute to the advancement of next-generation semiconductor packaging technologies through the supply of these materials.

Under the JX Advanced Metals Group Long-Term Vision 2040, the JX Advanced Metals Group will continue to contribute to societal development and innovation by developing and supplying advanced materials that support the evolution of cutting-edge technologies, including semiconductors.

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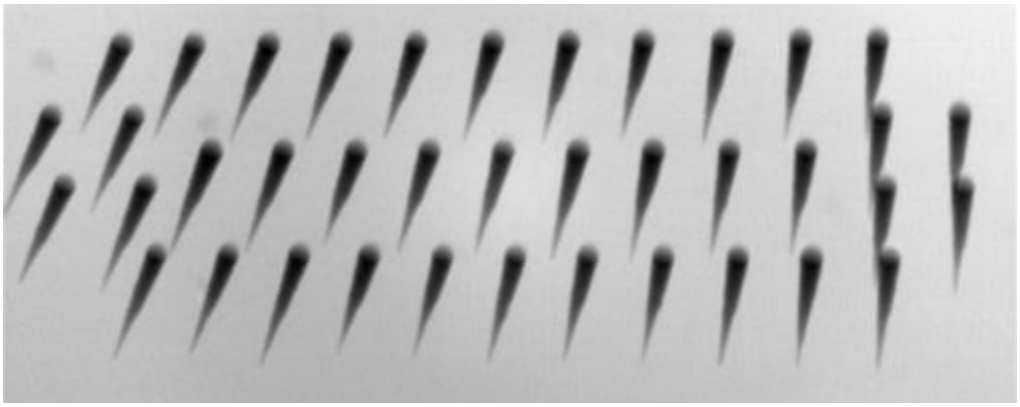
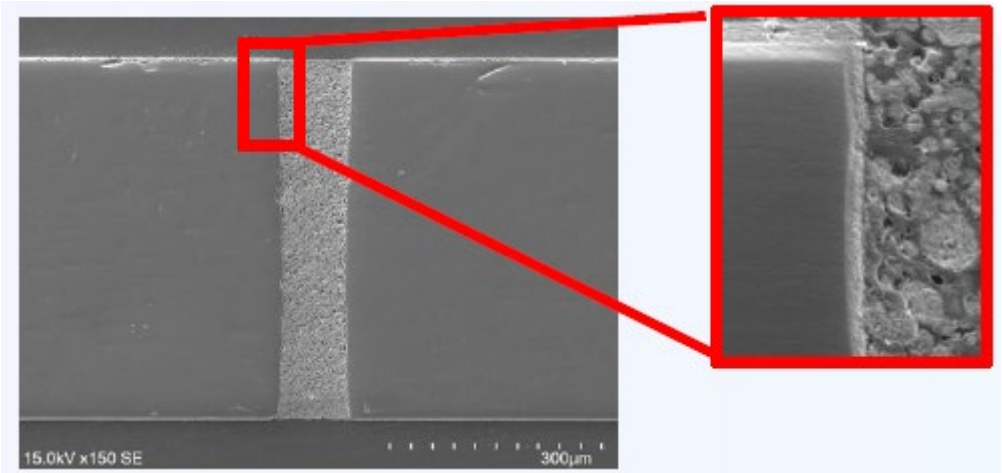


Project results presented at IMPACT 2026 (use of JX Advanced Metals' sputtering targets):
Formation of seed layers on a glass interposer



TATSUTA's conductive paste was used in the filling process for TGVs formed in a glass core substrate.



Presentation of project results at IMPACT 2026 (use of TATSUTA's conductive paste)

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